

In re Patent Application of:
CHARLES CARPENTER
Serial No. 09/864,918
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1. A method for manufacturing individual surface acoustic wave (SAW) devices, the method comprising the steps of:

forming a unitary array of a material having opposing first and second surfaces and plural spaced cavities extending into the array from the first surface, each cavity dimensioned to receive a SAW die therein;

forming a recess at each cavity from the first surface, each recess dimensioned to receive a lid within the recess;

providing at least two conductive paths from the interior of each cavity to a surface of the array;

inserting and attaching a SAW die face down into each of a plurality of the cavities, each SAW die having conductive means electrically contacting the conductive paths within the interior of the corresponding cavity after insertion;

sealing a lid in the recess over each inserted SAW die; and then

separating the array into individual SAW devices along separation lines between adjacent cavities.

6. The method recited in Claim 1, wherein the lid sealing step comprises the steps of:

placing a lid over each cavity;

placing a sealing material about the periphery of each lid; and then

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treating the package array-lids combination so as to seal each lid with the sealing material.

11. The method recited in Claim 1, further comprising the steps of:

placing a continuous tape across the first surface and the sealed lids prior to the separating step;

undertaking the separating step from the second surface while maintaining continuity of the tape across the first surface; and then removing the individual components from the tape.

12. The method recited in Claim 1, further comprising the step of forming the unitary array from a non-conductive material.

13. The method recited in Claim 12, wherein the unitary array comprises a ceramic.

15. The method recited in Claim 1, wherein the lid sealing step comprises the step of hermetically sealing the cavity from an ambient environment.

19. An assembly for manufacturing individual surface acoustic wave (SAW) devices comprising:

a unitary array of a nonconductive material having opposing first and second surfaces and plural spaced cavities extending into the array from the first surface, a plurality of the cavities having a SAW die inserted therein;

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a recess at each cavity extending from the first surface, each recess dimensioned to receive a lid within the recess;

means providing at least two electrically conductive paths from the SAW die within each cavity to an outer surface of the array;

a lid sealed in each recess over an inserted SAW die and the corresponding cavity; and

wherein the array may be separated into individual SAW devices along separation lines between adjacent cavities.

Ind B1 **Remarks**

Original Claims 3-5, 14, and 16-18 have been cancelled.

Claims 1-4, 6-15, 19, and 20 remain in the case.

No new matter has been added by this amendment.

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "**Version With Markings to Show Changes Made.**"